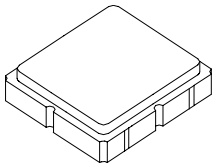
Preliminary

SF2215E

1960 MHz SAW Filter

- ***Low-loss 1960 MHz Filter***
- ***Complies with Directive 2002/95/EC (RoHS)***



SM3030-6

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	+10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-20 to +75	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 cycles/10 seconds maximum	265	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			1960.0		MHz
Insertion Loss, 1927.5 to 1992.5 MHz	IL			2.7	4.0	dB
Peak-to-Peak Amplitude Ripple, 1927.5 to 1992.5 MHz				1.3	2.5	dB
Input/Output Return Loss, 1927.5 to 1992.5 MHz			7.4	2.5		
Attenuation, Referenced to 0 dB:						dB
DC to 1740 MHz			20	31		
1740 to 1801 MHz			30	36		
1801 to 1880 MHz			20	41		
2040 to 2120 MHz			25	40		
2120 to 2500 MHz			31	38		
3700 to 4000 MHz			25	32		
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		Ω

Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	951, YWWS
Standard Reel Quantity Reel Size 7 inch	500 Pieces/Reel
Reel Size 13 inch	3000 Pieces/Reel

Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others

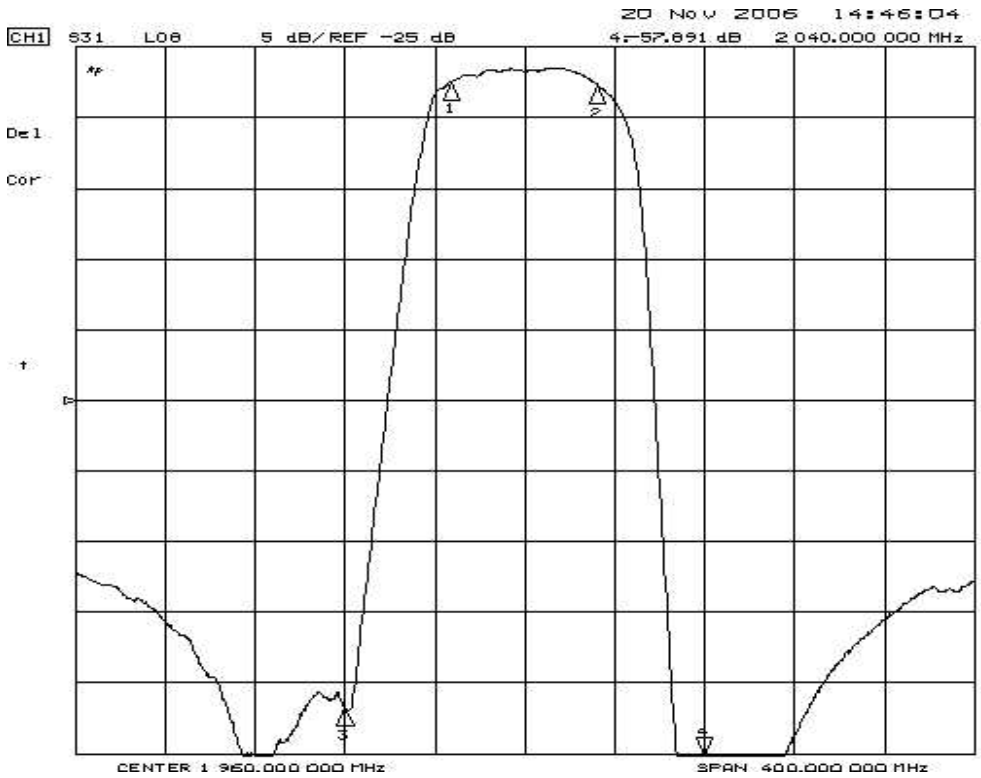
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

Notes:

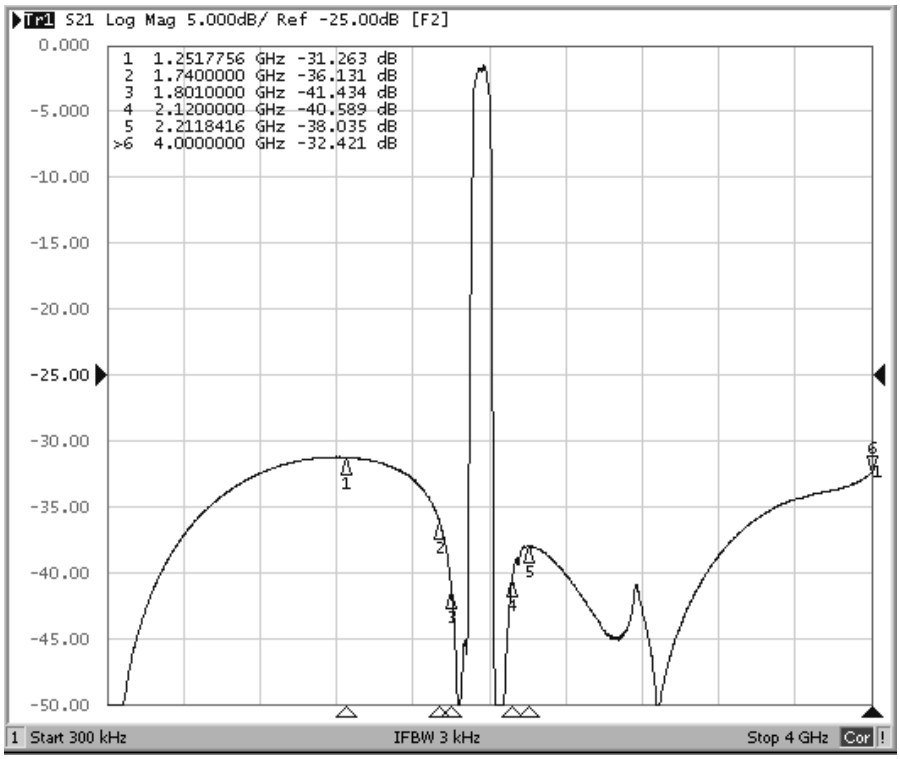
1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.
8. RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.

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Filter Passband Response

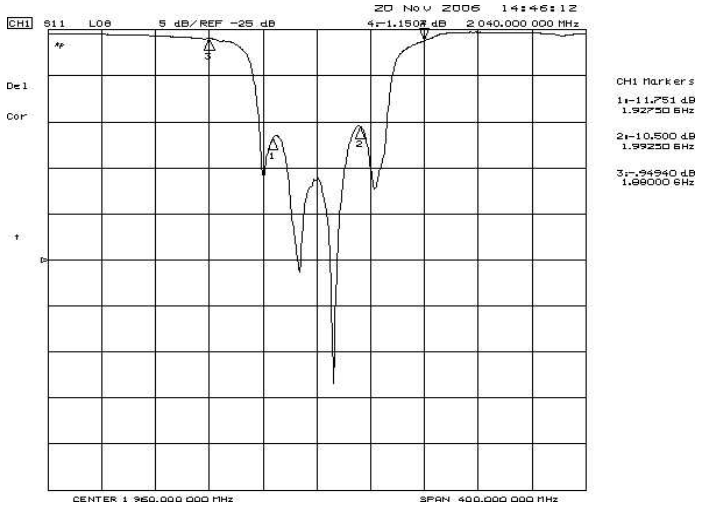


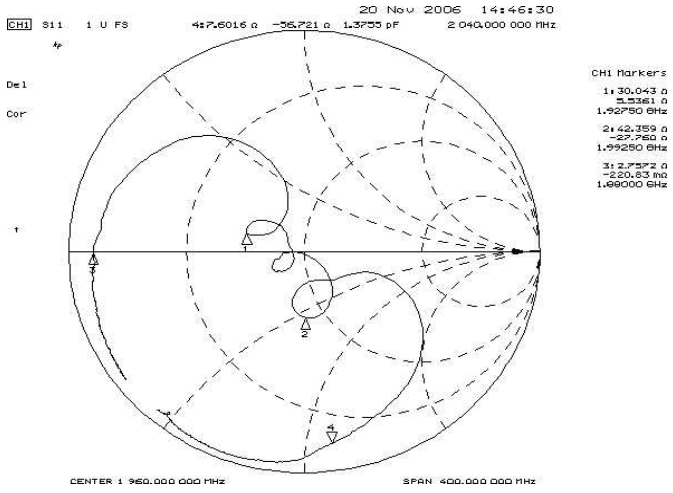
Filter Broadband Response



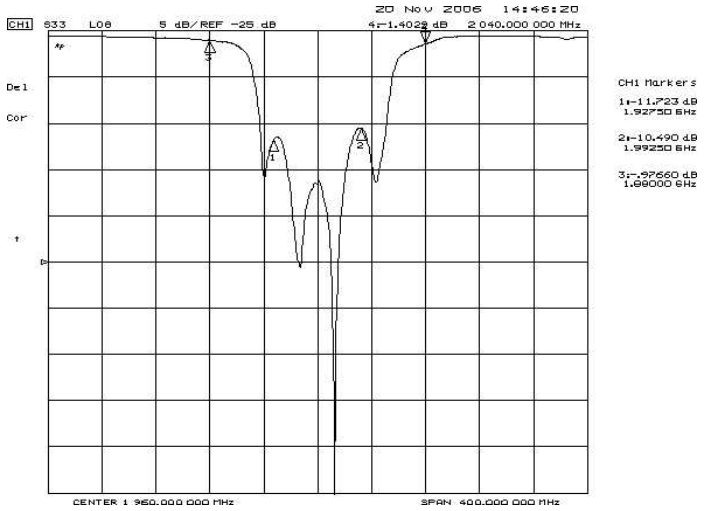
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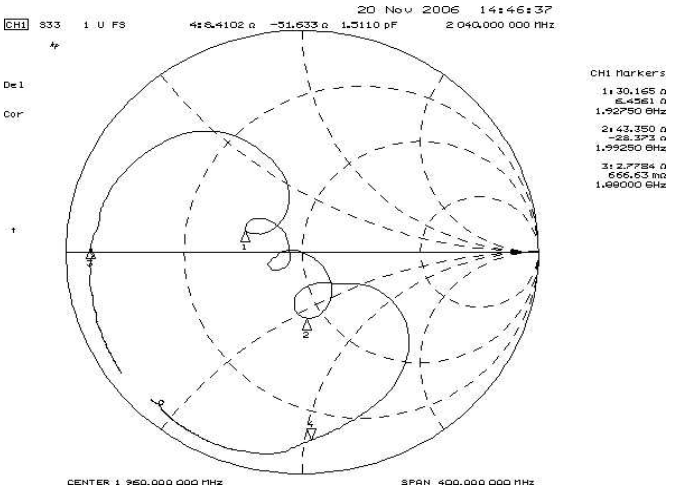
Filter Input VSWR and S_{11} Plots





Filter Output VSWR and S_{22} Plots

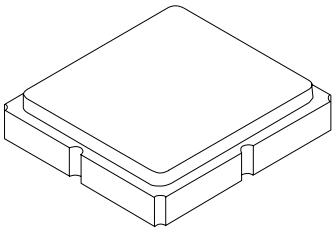


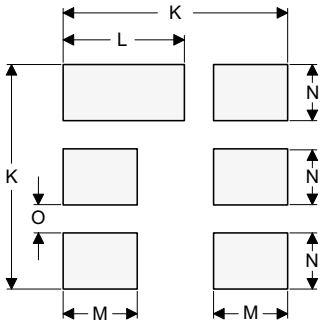


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SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case
3.0 X 3.0 mm Nominal Footprint





PCB Footprint Top View

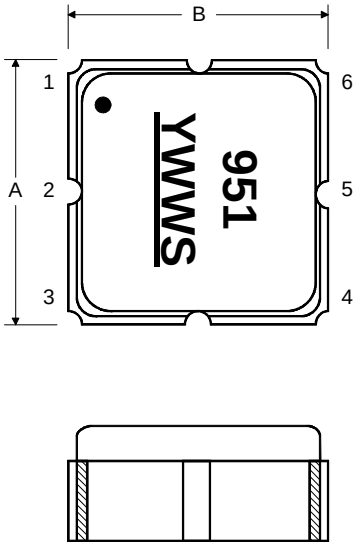
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

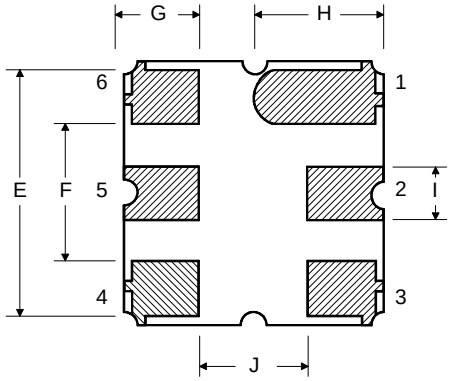
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel
Lid Plating	2.0 to 3.0 µm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

TOP VIEW

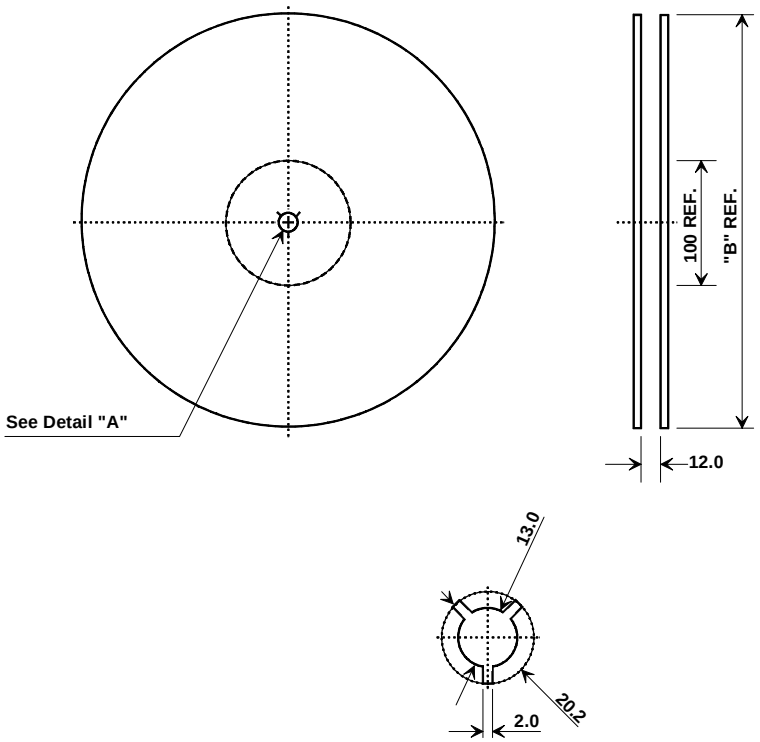


BOTTOM VIEW



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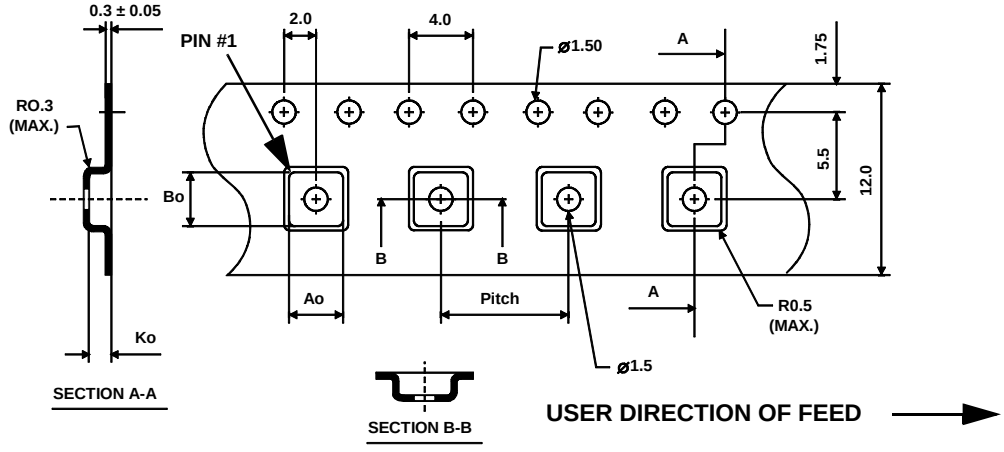
Tape and Reel Specifications



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



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